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Part Number: [73944-6216](#)
Status: **Active**
Overview: HDM®
Description: 2.00mm Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits

Documents:

[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

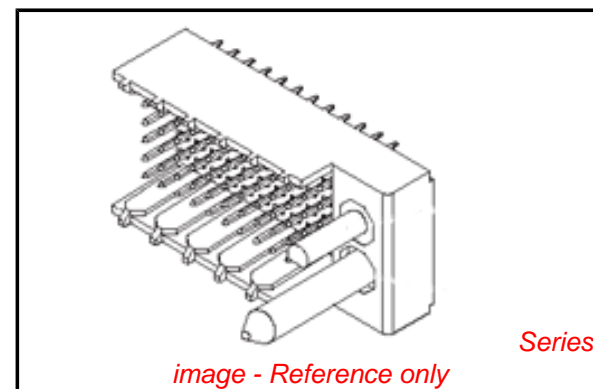
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73944](#)
 Application Backplane
 Component Type PCB Header
 Overview [HDM®](#)
 Product Name HDM®
 Style N/A
 UPC 800753005587

Physical

Circuits (Loaded) 72
 Circuits (maximum) 72
 Color - Resin Black, Natural
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part Yes
 Keying to Mating Part Yes
 Material - Metal Phosphor Bronze, Stainless Steel
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Net Weight 5.394/g
 Number of Columns 12
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator Yes
 PCB Retention None
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 2.540µm
 Polarized to PCB No
 Stackable No
 Surface Mount Compatible (SMC) No
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole



EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Low-Halogen Status Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73944Series](#)

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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